



# RS4GT126 Quadruple Bus Buffer Gate With 3-State Outputs

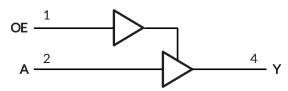
#### 1 FEATURES

- Operating Voltage Range: 2V to 5.5V
- Low Power Consumption: 1μA (Max)
- Operating Temperature Range: -40°C to +125°C
- Inputs Are TTL-Voltage Compatible
- ±32mA Output Drive at Vcc=5.0V
- Latch-up Performance Exceeds 100mA
- Micro SIZE PACKAGES: SOP14 and TSSOP14

#### 2 APPLICATIONS

- AV Receiver
- Cable Modem Termination Systems
- Digital Picture Frame (DPF)
- High-Speed Data Acquisition and Generation
- Motor Controls: High-Voltage
- Personal Navigation Device (GPS)
- Portable Media Player
- Video Communication Systems

#### **Simplified Schematic**



#### **3 DESCRIPTIONS**

The quadruple buffer is designed for 2V to 5.5V  $V_{CC}$  operation. The RS4GT126 device is quadruple line driver with 3-state output. The output is disabled when the output-enable input is low.

This device is fully specified for partial-power-down applications using loff. The loff circuitry disables the outputs, preventing damaging current backflow through the device when it is powered down.

To ensure the high-impedance state during power up or power down, OE should be tied to GND through a pulldown resistor, the minimum value of the resistor is determined by the current-sourcing capability of the driver.

The RS4GT126 is available in Green SOP14 and TSSOP14 packages. It operates over an ambient temperature range of -40°C to +125°C.

#### **Device Information (1)**

PART NUMBER	PACKAGE	BODY SIZE (NOM)
RS4GT126	SOP14	8.65mm×3.90mm
K34G1120	TSSOP14	5.00mm×4.40mm

For all available packages, see the orderable addendum at the end of the data sheet.

#### **FUNCTION TABLE**

INP	OUTPUT	
OE	Α	Υ
Н	Н	Н
Н	L	L
L	X	Z

H=HIGH Logic Level L =LOW Logic Level X=Don't Care Z=High-impedance OFF-state



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**4 Revision History**Note: Page numbers for previous revisions may different from page numbers in the current version.

Version	Change Date	Change Item			
A.1	2023/11/08	Initial version completed			
A.1.1	2024/02/29	Modify packaging naming			



#### 5 PACKAGE/ORDERING INFORMATION (1)

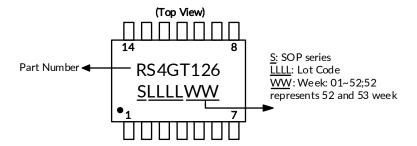
PRODUCT	ORDERING NUMBER	TEMPERATURE RANGE	PACKAGE LEAD	PACKAGE MARKING (2)	MSL <sup>(3)</sup>	PACKAGE OPTION
DC4CT40/	RS4GT126XP	-40°C ~+125°C	SOP14	RS4GT126	MSL3	Tape and Reel,4000
RS4GT126	RS4GT126XQ	-40°C ~+125°C	TSSOP14	RS4GT126	MSL3	Tape and Reel,4000

#### NOTE:

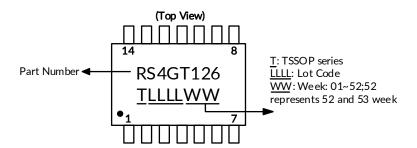
- (1) This information is the most current data available for the designated devices. This data is subject to change without notice and revision of this document. For browser-based versions of this data sheet, refer to the right-hand navigation.
- (2) There may be additional marking, which relates to the lot trace code information (data code and vendor code), the logo or the environmental category on the device.
- (3) MSL, The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications.

#### **Marking Information**

(1) SOP14

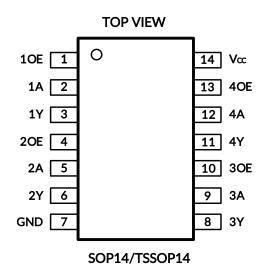


(2) TSSOP14





#### **6 PIN CONFIGURATIONS**



**PIN DESCRIPTION** 

I III DESCRII I IOII			
PIN	NANAF	L(O T)(DE (1)	FUNCTION
SOP14/TSSOP14	NAME	I/O TYPE (1)	FUNCTION
1	10E	1	Output Enable for buffer 1
2	1A	I	Input of buffer 1
3	1Y	0	Output of buffer 1
4	20E	I	Output Enable for buffer 2
5	2A	I	Input of buffer 2
6	2Y	0	Output of buffer 2
7	GND	-	Ground
8	3Y	0	Output of buffer 3
9	3A	1	Input of buffer 3
10	3OE	1	Output Enable for buffer 3
11	4Y	0	Output of buffer 4
12	4A	I	Input of buffer 4
13	40E	1	Output Enable for buffer 4
14	Vcc	-	Power Supply

<sup>(1)</sup> I=input, O=output.



#### 7 Specifications

#### 7.1 Absolute Maximum Ratings (1)

over operating free-air temperature range (unless otherwise noted) (1) (2)

			MIN	MAX	UNIT
V <sub>CC</sub>	Supply voltage range		-0.5	6.5	٧
Vı	Input voltage range (2)		-0.5	6.5	٧
Vo	Voltage range applied to any output in the high-impedan	ce or power-off state <sup>(2)</sup>	-0.5	6.5	V
Vo	Vo Voltage range applied to any output in the high or low state (2)(3)				V
lıĸ	Input clamp current V <sub>I</sub> <0			-50	mA
Іок	Output clamp current		-50	mA	
lo	Continuous output current			±50	mA
	Continuous current through V <sub>CC</sub> or GND			±100	mA
0	Declare the great increases (4)	SOP14		105	°C/W
ALθ	Package thermal impedance (4)  TSSOP14			90	-C/VV
٦	T <sub>J</sub> Junction temperature <sup>(5)</sup>				°C
Tstg	T <sub>stg</sub> Storage temperature				°C

<sup>(1)</sup> Stresses beyond those listed under Absolute Maximum Ratings may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under Recommended Operating Conditions is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- (2) The input and output negative-voltage ratings may be exceeded if the input and output current ratings are observed.
- (3) The value of  $V_{CC}$  is provided in the Recommended Operating Conditions table.
- (4) The package thermal impedance is calculated in accordance with JESD-51.
- (5) The maximum power dissipation is a function of  $T_{J(MAX)}$ ,  $R_{\theta JA}$ , and  $T_A$ . The maximum allowable power dissipation at any ambient temperature is  $P_D = (T_{J(MAX)} T_A) / R_{\theta JA}$ . All numbers apply for packages soldered directly onto a PCB.

#### 7.2 ESD Ratings

The following ESD information is provided for handling of ESD-sensitive devices in an ESD protected area only.

			VALUE	UNIT
		Human-body model (HBM), MIL-STD-883K METHOD 3015.9	±2000	
V <sub>(ESD)</sub>	Electrostatic discharge	Charged-device model (CDM), ANSI/ESDA/JEDEC JS-002-2018	±1000	V
		Machine Model (MM), JESD22-A115C (2010)	±200	



#### **ESD SENSITIVITY CAUTION**

ESD damage can range from subtle performance degradation to complete device failure. Precision integrated circuits may be more susceptible to damage because very small parametric changes could cause the device not to meet its published specifications.

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#### **8 ELECTRICAL CHARACTERISTICS**

over recommended operating free-air temperature range (TYP values are at T<sub>A</sub> = +25°C, unless otherwise noted.) (1)

#### **8.1 Recommended Operating Conditions**

PARAMETER	SYMBOL	TEST CONDITIONS	MIN	MAX	UNIT
Supply voltage	Vcc	Operating	2	5.5	V
		V <sub>CC</sub> =2V	1		
High-level input voltage	VIH	V <sub>CC</sub> =3.3V	1.5		V
		V <sub>CC</sub> =4.5V to 5.5V	2		
		V <sub>CC</sub> =2V		0.3	
Low-level input voltage	VIL	V <sub>CC</sub> =3.3V		0.55	V
		V <sub>CC</sub> =4.5V to 5.5V		0.8	
Input voltage	Vı		0	5.5	V
Output voltage	Vo		0	Vcc	V
Input transition rise or fall	t <sub>r</sub> , t <sub>f</sub>	V <sub>CC</sub> =2.0V to 5.5V		5	ns/V
Operating temperature	$T_A$		-40	125	°C

<sup>(1)</sup> All unused inputs of the device must be held at Vcc or GND to ensure proper device operation.

#### **8.2 DC Characteristics**

PA	RAMETER	TEST CONDITIONS	Vcc	TEMP	MIN <sup>(2)</sup>	TYP <sup>(3)</sup>	MAX <sup>(2)</sup>	UNIT
		I <sub>OH</sub> = -100μA	2V to 5.5V		V <sub>CC</sub> -0.1			
		I <sub>OH</sub> = -8mA	2V		1.2			
	V	I <sub>OH</sub> = -24mA	3.3V	Full	1.9			V
	V <sub>OH</sub>		4.5V	Full	2.4			\ \ \
		I <sub>OH</sub> = -32mA	5V		2.3			
			5.5V		3.8			
		I <sub>OL</sub> = 100μA	2V to 5.5V				0.1	
		I <sub>OL</sub> = 8mA	2V				0.45	
	V	I <sub>OL</sub> = 24mA	3.3V	Full			0.3	V
	$V_{OL}$		4.5V				0.4	
		I <sub>OL</sub> = 32mA	5V				0.55	
			5.5V	0.9		0.55		
	A or OE	A or OE		+25°C		±0.1	±1	^
lı	inputs	V <sub>I</sub> =5.5V or GND	0V to 5.5V	Full			±5	μΑ
	1	\\\\	0)/	+25°C		±0.1	±1	
	$I_{\text{off}}$ $V_{1}$ or $V_{0}$ =5.5 $V$		0V	Full			±10	μΑ
l		V 5 5V CND 1 0	2)/+- 5 5)/	+25°C		0.1	1	
Icc		V <sub>I</sub> =5.5V or GND, I <sub>O</sub> =0	2V to 5.5V	Full			10	μΑ
One input at Vcc-3.4V, Other inputs at Vcc or GND		One input at V <sub>CC</sub> -3.4V, Other inputs at V <sub>CC</sub> or GND	5.5V	Full			500	μΑ
Ci (Inp	ut Capacitance)	V <sub>CC</sub> =0V, f = 10MHz	0V	+25°C		4		pF

<sup>(1)</sup> All unused inputs of the device must be held at  $V_{CC}$  or GND to ensure proper device operation.

<sup>(2)</sup> This parameter is ensured by design and/or characterization and is not tested in production.

<sup>(3)</sup> Typical values represent the most likely parametric norm as determined at the time of characterization. Actual typical values may vary over time and will also depend on the application and configuration.



#### 8.3 AC Characteristics

PAR	AMETER	SYMBOL	TEST CO	ONDITIONS	MIN <sup>(2)</sup>	<b>TYP</b> (3)	MAX <sup>(2)</sup>	UNIT
			V <sub>CC</sub> =2.0V±0.2V	C <sub>L</sub> =30pF, R <sub>L</sub> =500Ω		15.5		
Propag	gation Delay	$t_{pd}$	V <sub>CC</sub> =3.3V±0.3V	C <sub>L</sub> =50pF, R <sub>L</sub> =500Ω		9.7		ns
			V <sub>CC</sub> =5.0V±0.5V	C <sub>L</sub> =50pF, R <sub>L</sub> =500Ω		7.5		
			V <sub>CC</sub> =2.0V±0.2V	C <sub>L</sub> =30pF, R <sub>L</sub> =500Ω		10.8		
Ena	ble Time	$t_{en}$	V <sub>CC</sub> =3.3V±0.3V	C <sub>L</sub> =50pF, R <sub>L</sub> =500Ω		7.4		ns
			V <sub>CC</sub> =5.0V±0.5V	C <sub>L</sub> =50pF, R <sub>L</sub> =500Ω		6.04		
			V <sub>CC</sub> =2.0V±0.2V	C <sub>L</sub> =30pF, R <sub>L</sub> =500Ω		13.6		
Disa	able Time	$t_{dis}$	V <sub>CC</sub> =3.3V±0.3V	C <sub>L</sub> =50pF, R <sub>L</sub> =500Ω		9.7		ns
			V <sub>CC</sub> =5.0V±0.5V	C <sub>L</sub> =50pF, R <sub>L</sub> =500Ω		7.7		
Power	Output enabled					40		-
dissipation capacitance	Output disabled	$C_pd$	V <sub>CC</sub> =5V	f=10MHz		4		pF

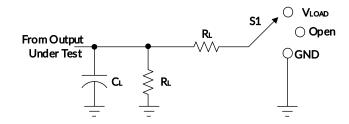
<sup>(1)</sup> All unused inputs of the device must be held at  $V_{CC}$  or GND to ensure proper device operation.

<sup>(2)</sup> This parameter is ensured by design and/or characterization and is not tested in production.

<sup>(3)</sup> Typical values represent the most likely parametric norm as determined at the time of characterization. Actual typical values may vary over time and will also depend on the application and configuration.

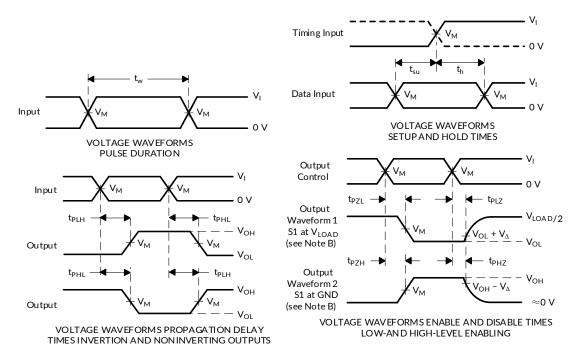


#### **9 Parameter Measurement Information**



TEST	<b>S1</b>
tplH/tpHL	Open
tplz/tpzl	$V_{LOAD}$
t <sub>PHZ</sub> /t <sub>PZH</sub>	GND

Vcc	INPUTS		V	V	C.	D.	VΔ
	Vı	t <sub>r</sub> /t <sub>f</sub>	Vм	VLOAD	C∟	RL	VΔ
2.0V±0.2V	Vcc	≤2ns	Vcc/2	2 x Vcc	30pF	500Ω	0.15V
3.3V±0.3V	3V	≤2.5ns	1.5V	6V	50pF	500Ω	0.3V
5V±0.5V	Vcc	≤2.5ns	Vcc/2	2 x Vcc	50pF	500Ω	0.3V



NOTES: A. C<sub>L</sub> includes probe and jig capacitance.

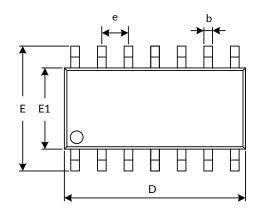
- B. Waveform 1 is for an output with internal conditions such that the output is low, except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR  $\leq$  10 MHz,  $Z_0 = 50 \Omega$ .
- D. The outputs are measured one at a time, with one transition per measurement.
- E.  $t_{PLZ}$  and  $t_{PHZ}$  are the same as  $t_{dis}$ .
- F.  $t_{PZL}$  and  $t_{PZH}$  are the same as  $t_{en}$ .
- G.  $t_{\text{PLH}}$  and  $t_{\text{PHL}}$  are the same as  $t_{\text{pd}}.$
- H. All parameters and waveforms are not applicable to all devices.

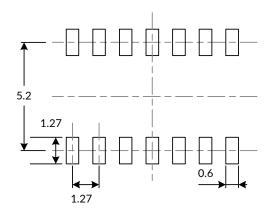
Figure 1. Load Circuit and Voltage Waveforms

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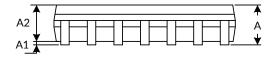


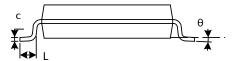
#### 10 PACKAGE OUTLINE DIMENSIONS SOP14 (3)





RECOMMENDED LAND PATTERN (Unit: mm)





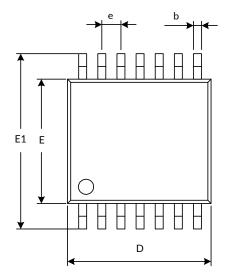
Symbol	Dimensions I	n Millimeters	Dimensions In Inches			
	Min	Max	Min	Max		
A <sup>(1)</sup>		1.750		0.069		
A1	0.100	0.250	0.004	0.010		
A2	1.300	1.500	0.051	0.059		
b	0.390	0.470	0.015	0.019		
С	0.200	0.240	0.008	0.009		
D <sup>(1)</sup>	8.550	8.750	0.336	0.344		
е	1.270(	BSC) (2)	0.050(BSC) (2)			
E	5.800	6.200	6.200 0.228			
E1 <sup>(1)</sup>	3.800	4.000	0.150	0.157		
L	0.500	0.800	0.020	0.031		
θ	0°	8°	0°	8°		

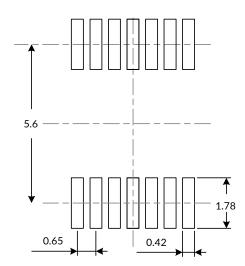
#### NOTE:

- Plastic or metal protrusions of 0.15mm maximum per side are not included.
   BSC (Basic Spacing between Centers), "Basic" spacing is nominal.
   This drawing is subject to change without notice.



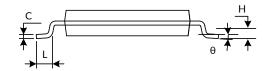
#### **TSSOP14**(3)





RECOMMENDED LAND PATTERN (Unit: mm)





Symbol	Dimensions I	n Millimeters	Dimensions In Inches			
	Min	Max	Min	Max		
A <sup>(1)</sup>		1.200		0.047		
A1	0.050	0.150	0.002	0.006		
A2	0.900	1.050	0.035	0.041		
b	0.200	0.300	0.008	0.012		
С	0.130	0.170	0.005	0.007		
D (1)	4.860	5.100	0.191	0.201		
E <sup>(1)</sup>	4.300	4.500	0.169	0.177		
E1	6.200	6.600	0.244	0.260		
е	0.650(	BSC) (2)	0.026(BSC) (2)			
L	0.450	0.750	0.018	0.030		
Н	0.250	)(TYP)	0.010(TYP)			
θ	0°	8°	0°	8°		

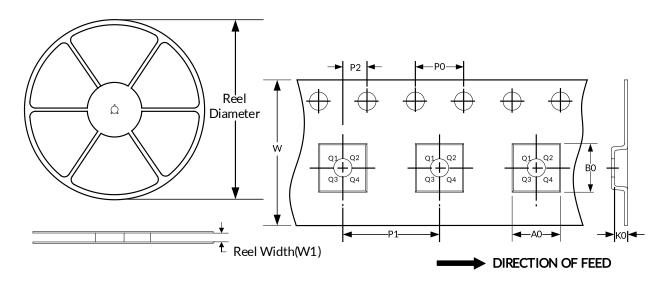
#### NOTE:

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- 2. BSC (Basic Spacing between Centers), "Basic" spacing is nominal.
  3. This drawing is subject to change without notice.



## 11 TAPE AND REEL INFORMATION REEL DIMENSIONS

#### **TAPE DIMENSION**



NOTE: The picture is only for reference. Please make the object as the standard.

#### **KEY PARAMETER LIST OF TAPE AND REEL**

Package Type	Reel Diameter	Reel Width(mm)	A0 (mm)	B0 (mm)	K0 (mm)	P0 (mm)	P1 (mm)	P2 (mm)	W (mm)	Pin1 Quadrant
SOP14	13"	16.4	6.60	9.30	2.10	4.0	8.0	2.0	16.0	Q1
TSSOP14	13"	12.4	6.95	5.60	1.20	4.0	8.0	2.0	12.0	Q1

#### NOTE:

- 1. All dimensions are nominal.
- 2. Plastic or metal protrusions of 0.15mm maximum per side are not included.



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